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Thermosense: Thermal Infrared Applications XLI

Jaap de Vries
Beate Oswald-Tranta
Editors

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Contents

v	<i>Authors</i>
vii	<i>Conference Committee</i>

MEDICAL APPLICATIONS

11004 04	Use of equivalent wave field transform in evaluating dynamic thermal tomography of infrared breast images [11004-4]
11004 05	Detection of syrxinx in thermographic images of canines with Chiari malformation using MATLAB CVIP toolbox GUI [11004-5]

INDUSTRIAL APPLICATION

11004 06	Improving thermal substation inspections utilising machine learning [11004-6]
11004 07	Advanced signal processing applied to thermographic inspection of petrochemical furnaces [11004-7]
11004 08	Improvements in the design of thermal-infrared radiation thermometers and sensors [11004-8]
11004 09	Thermal conductivity of refractory coatings for foundry applications [11004-9]
11004 0A	The use of drones, thermography, and other optical measuring devices [11004-10]

RESEARCH TOPICS

11004 0B	Research on the stability of readout circuit based on single grade OP-AMP for IR detector [11004-11]
11004 0D	A comparison study of additive manufacturing techniques applied to chalcogenide glass [11004-13]

AEROSPACE APPLICATIONS

11004 0E	Estimation of delamination crack depth using passive thermography [11004-14]
11004 0F	Quadrupole simulations of thermographic inspections of impacted composites [11004-15]

- 11004 OG **Thermosonic imaging for rapid full-field nondestructive inspection of composite structures** [11004-16]
- 11004 OH **Fatigue behaviour assessment of automated fiber placement composites by adopting the thermal signal analysis** [11004-17]
- 11004 OI **Autonomous systems thermographic NDT of composite structures** [11004-18]

NDT

- 11004 OJ **Flying-spot thermography: measuring the in-plane (an)isotropic thermal diffusivity of large and complex parts** [11004-19]
- 11004 OK **Flying-spot thermography: sizing the thermal resistance of infinite vertical cracks** [11004-20]
- 11004 OL **Flash and inductive thermography for CFRP inspection** [11004-21]
- 11004 OM **The influence of the truncation window size on the quantitative thermographic results after a pulsed test on an aluminium sample: comparison among different post-processing algorithms** [11004-22]
- 11004 ON **A new thermographic procedure for the non-destructive evaluation of RSW joints** [11004-23]
- 11004 OO **Study of the thermo-elastic stress analysis (TSA) sensitivity in the evaluation of residual stress in non-ferrous metal** [11004-25]
- 11004 OQ **Low cost high resolution transient thermography imaging based on equivalent wave field transform** [11004-100]

POSTER SESSION

- 11004 OS **Development of a new methodology for thermal image reconstruction** [11004-30]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Avdelidis, N. P., 0I
Batsale, J. C., 0J
Bedoya, A., 0J
Bison, Paolo, 09
Carrasco, Joaquin, 06
Chen, Yongping, 0B
Cotton, Ian, 06
Cuellar, J., 05
D'Accardi, Ester, 0M, 0N
Deane, S., 0I
Deegan, J., 0D
De Finis, R., 0H, 0O
Di Carolo, F., 0O
Eppeldauer, George P., 08
Exarchos, D. A., 0S
Ferrarini, Giovanni, 09
Galietti, Umberto, 0H, 0M, 0N, 0O
Gardner, Richard, 06
Gershenson, J., 04
Gershenson, Meir, 04, 0Q
González, J., 0J, 0K
Hassinen, Marko, 0A
Howell, Patricia A., 0F
Huang, Zhiwei, 0B
Huot, Alexandrine, 07
Ibarra-Castaneda, C., 0I
Jackson, Wade C., 0E
Karlapalem, A., 05
Kauppinen, Timo, 0A
Khromchenko, Vladimir B., 08
Kordatos, E. Z., 0S
Kordatou, T. Z., 0S
Li, Wuying, 0B
Lin, Bin, 0G
Lindberg, G. P., 0D
Long, Michael, 0G
Lopez, Fernando, 07
Maldague, X. P. V., 0I
Marino, D. J., 05
Matikas, T. E., 0S
Mendioroz, A., 0J, 0K
Musgraves, J. D., 0D
Oswald-Tranta, Beate, 0L
Palumbo, Davide, 0M, 0N, 0O
Podd, Frank, 06
Posio, Mikko, 0A
Pradere, C., 0J
Ramsey, J. L., 0D
Rose, Cheryl A., 0E
Rossi, Stefano, 09
Sackman, J., 05
Salazar, A., 0J, 0K
Savolainen, Marko, 0A
Schledjewski, Ralf, 0L
Siikanen, Sami, 0A
Skog, Gedi, 0A
Sommier, A., 0J
Stockton, Greg, 0A
Straker, Alastair, 06
Tamborrino, Rosanna, 0M
Tsourdos, A., 0I
Tuschl, Christoph, 0L
Tzitzilonis, V., 0I
Umbaugh, S. E., 05
Wachtel, P. F., 0D
Williamson, A., 0I
Winfree, William P., 0F
Xiang, Dan, 0G
Xu, Xing, 0B
Yazdani Nezhad, H., 0I
Yoon, Howard W., 08
Yuan, Honghui, 0B
Zalameda, Joseph N., 0E, 0F
Zhang, H., 0I
Zhong, Yanping, 0B

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- 1 Vendor Presentation and Reception: Thermosense XLI
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- 2 Medical Applications
Arantza Mendioroz, Universidad del País Vasco (Spain)
Jaap de Vries, FM Global (United States)
- 3 Industrial Application
Gary E. Strahan, Infrared Cameras, Inc. (United States)
Gregory R. Stockton, Stockton Infrared Thermographic Services, Inc.
(United States)
- 4 Research Topics
Jaap de Vries, FM Global (United States)
Giovanni Ferrarini, CNR-Istituto per le Tecnologie della Costruzione
(Italy)
- 5 Aerospace Applications
Joseph N. Zalameda, NASA Langley Research Center (United States)
Nicolas P. Avdelidis, National Technical University of Athens (Greece)
- 6 NDT
Beate Oswald-Tranta, Montan Universität Leoben (Austria)
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